

TP70H300G4JSGB

700V SuperGaN® GaN FET in PQFN 5 × 6 Industry Standard Package (source tab)

Description

The TP70H300G4JSGB 700V, 240mΩ Gallium Nitride (GaN) FET is a normally-off device that uses Renesas' Gen IV platform. It combines a state-of-the-art high-voltage GaN HEMT with a low-voltage silicon MOSFET to offer superior reliability and performance while enabling reduced system size and cost.

The Gen IV SuperGaN® platform uses advanced epi and patented design technologies to simplify manufacturability while improving efficiency over silicon via lower gate charge, output capacitance, crossover loss, and reverse recovery charge.

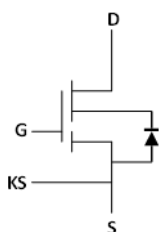
Benefits

- Achieves increased efficiency in both hard- and soft-switched circuits
 - Increased power density
 - Reduced system size and weight
 - Overall lower system cost
- Easy to drive with Si gate drivers

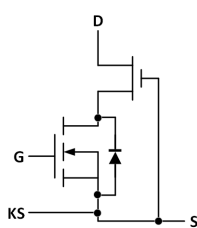
Product and Schematic Diagrams



TP70H300G4JSGB PQFN 5 × 6 IP



Cascode Schematic Symbol



Cascode Device Structure
(MOSFET has integrated ESD Protection Circuit)

Features

- Gen IV technology
- JEDEC-qualified GaN technology
- Dynamic RDS(on)eff production tested
- Robust design, defined by
 - Transient over-voltage capability
 - Operation with E-mode gate drivers without need for Zener protection.
- Reduced crossover loss
- Negligible Qrr
- RoHS compliant and Halogen-free packaging
- 2kV HBM ESD rating

Applications

- Consumer
- Power adapters
- Low power SMPS
- Lighting



Key Specifications

V_{DS} (V)	700
$V_{DSS(TR)}$ (V)	800
$R_{DS(on)}$ (mΩ) maximum ^[1]	312
Q_{OSS} (nC) typical	17
Q_G (nC) typical	5.4

1. Dynamic RDS(on); see Figure 17 and Figure 18.

Contents

1. Pin Information	3
1.1 Pin Assignments	3
1.2 Pin Descriptions	3
2. Specifications	4
2.1 Absolute Maximum Ratings	4
2.2 Thermal Specifications	4
2.3 Electrical Specifications – Forward Device	5
2.4 Electrical Specifications – Reverse Device	6
3. Typical Performance Graphs	7
4. Test Circuits and Waveforms	9
5. Package Outline Drawings	10
6. Related Information	11
7. Ordering Information	11
8. Revision History	11

Figures

Figure 1. Pin Assignments – Bottom View	3
Figure 2. Typical Output Characteristics, $T_J = 25^{\circ}\text{C}$	7
Figure 3. Typical Output Characteristics, $T_J = 150^{\circ}\text{C}$	7
Figure 4. Typical Transfer Characteristics	7
Figure 5. Normalized On-resistance	7
Figure 6. Typical Capacitance	7
Figure 7. Typical C_{OSS} Stored Energy	7
Figure 8. Typical Q_{OSS}	8
Figure 9. Typical Gate Charge	8
Figure 10. Power Dissipation	8
Figure 11. Current Derating	8
Figure 12. Forward Characteristics of Rev. Diode	8
Figure 13. Transient Thermal Resistance	8
Figure 14. Safe Operating Area $T_C = 25^{\circ}\text{C}$	9
Figure 15. Switching Time Test Circuit	9
Figure 16. Switching Time Waveform	9
Figure 17. Dynamic $R_{DS(on)eff}$ Test Circuit	9
Figure 18. Dynamic $R_{DS(on)eff}$ Waveform	9
Figure 19. Package Outline Drawing – 5×6 PQFN	10

1. Pin Information

1.1 Pin Assignments

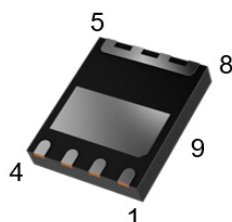


Figure 1. Pin Assignments – Bottom View

1.2 Pin Descriptions

Pin Number	Pin Name	Description
1, 2	NC	No connection.
3	KS	Kelvin source.
4	G	Gate.
5, 6, 7, 8	D	Drain.
9	S	Source.

2. Specifications

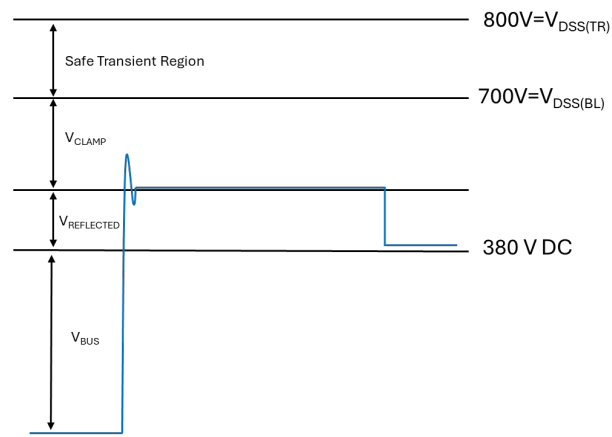
2.1 Absolute Maximum Ratings

($T_c = 25^\circ\text{C}$ unless otherwise stated.)

Caution: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

Symbol	Parameter	Minimum	Maximum	Unit
V_{DSS}	Drain to source voltage ($T_J = -55^\circ\text{C}$ to 150°C)	-	700	V
$V_{\text{DSS(TR)}, \text{ non-repetitive}}$	Transient drain to source voltage, non-repetitive ^[1]	-	800	
$V_{\text{DSS(TR)}, \text{ repetitive}}$	Transient drain to source voltage, repetitive ^[2]	-	750	
V_{GSS}	Gate to source voltage	-20	+20	
P_D	Maximum power dissipation at $T_c = 25^\circ\text{C}$	-	31.2	W
I_D	Continuous drain current at $T_c = 25^\circ\text{C}$ ^[3]	-	8	A
	Continuous drain current at $T_c = 100^\circ\text{C}$ ^[3]	-	5	A
I_{DM}	Pulsed drain current (pulse width: 10 μs)	-	30	A
T_J	Junction operating temperature	-55	+150	$^\circ\text{C}$
T_s	Storage temperature	-55	+150	$^\circ\text{C}$
T_{SOLD}	Reflow soldering temperature ^[4]	-	260	$^\circ\text{C}$

1. In off-state, spike duration < 30 μs , non-repetitive.
2. Off-state, spike duration < 5 μs .
3. Reflow MSL3.



2.2 Thermal Specifications

Symbol	Condition	Typical Value	Unit
R_{QJC}	Junction-to-case	4	$^\circ\text{C/W}$
R_{QJA}	Junction-to-ambient ^[1]	50	

1. Device on one layer epoxy PCB for source connection (vertical and without air stream cooling, with 6cm² copper area and 70 μm thickness).

2.3 Electrical Specifications – Forward Device

$T_J = 25^\circ\text{C}$ unless otherwise stated.

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
$V_{DSS(BL)}$	Maximum drain-source voltage	$V_{GS} = 0V$	700	-	-	V
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 0.5mA$	1.5	2.0	2.5	V
$\Delta V_{GS(th)}/T_J$	Gate threshold voltage temperature coefficient	-	-	-5.8	-	mV/ $^\circ\text{C}$
$R_{DS(on)eff}$	Drain-source on-resistance ^[1]	$V_{GS} = 6V, I_D = 5A$	-	240	312	m Ω
		$V_{GS} = 6V, I_D = 5A, T_J = 150^\circ\text{C}$	-	492	-	
I_{DSS}	Drain-to-source leakage current	$V_{DS} = 700V, V_{GS} = 0V$	-	1.2	12	μA
		$V_{DS} = 700V, V_{GS} = 0V, T_J = 150^\circ\text{C}$	-	8	-	
I_{GSS}	Gate-to-source forward leakage current ^[2]	$V_{GS} = 20V$	-	-	10	μA
	Gate-to-source reverse leakage current ^[2]	$V_{GS} = -20V$	-	-	-10	
I_{GSS}	Gate-to-source forward leakage current ^[2]	$V_{GS} = 6V$	-	-	0.1	μA
	Gate-to-source reverse leakage current ^[2]	$V_{GS} = -6V$	-	-	-0.1	
C_{ISS}	Input capacitance	$V_{GS} = 0V, V_{DS} = 400V, f = 1MHz$	-	487	-	pF
C_{OSS}	Output capacitance		-	16.3	-	
C_{RSS}	Reverse transfer capacitance		-	2	-	
$C_{O(er)}$	Output capacitance, energy related ^[3]	$V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V$	-	24	-	pF
$C_{O(tr)}$	Output capacitance, time related ^[4]	$V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V$	-	42	-	
Q_G	Total gate charge	$V_{DS} = 400V, V_{GS} = 0V \text{ to } 6V, I_D = 5A$	-	5.4	-	nC
Q_{GS}	Gate-source charge		-	1.5	-	
Q_{GD}	Gate-drain charge		-	2.3	-	
Q_{OSS}	Output charge	$V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V$	-	17	-	nC
$t_{D(on)}$	Turn-on delay	$V_{DS} = 400V, V_{GS} = 0V \text{ to } 6V, I_D = 5A, R_G = 20\Omega, ZFB = 120\Omega \text{ at } 100MHz$ (see Figure 15)	-	25	-	ns
t_R	Rise time		-	4.2	-	
$t_{D(off)}$	Turn-off delay		-	45.4	-	
t_F	Fall time		-	6.4	-	

1. Dynamic $R_{DS(on)}$, 100% tested; see [Figure 17](#) and [Figure 18](#) for conditions.
2. Including leakage current of the integrated ESD protection circuit.
3. Equivalent capacitance to give same stored energy from 0V to 400V.
4. Equivalent capacitance to give same charging time from 0V to 400V.

2.4 Electrical Specifications – Reverse Device

$T_J = 25^\circ\text{C}$ unless otherwise stated.

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
I_S	Reverse current	$V_{GS} = 0V$, $T_C = 100^\circ\text{C}$, $\leq 25\%$ duty cycle	-	-	5	A
V_{SD}	Reverse voltage ^[1]	$V_{GS} = 0V$, $I_S = 2.5A$	-	1.3	-	V
		$V_{GS} = 0V$, $I_S = 5 A$	-	1.9	-	

1. Includes dynamic $R_{DS(on)}$ effect.

Note: Reverse recovery charge is negligible enabled by the LV Si FET technology

3. Typical Performance Graphs

$T_c = 25^\circ\text{C}$ unless otherwise stated.

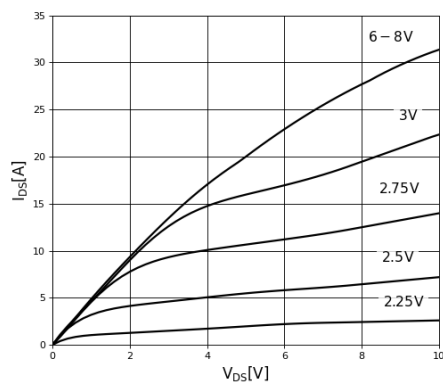


Figure 2. Typical Output Characteristics, $T_J = 25^\circ\text{C}$

Parameter: V_{GS}

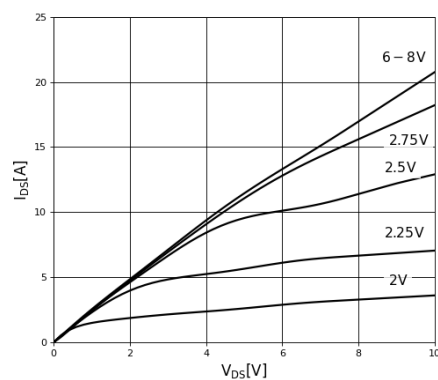


Figure 3. Typical Output Characteristics, $T_J = 150^\circ\text{C}$

Parameter: V_{GS}

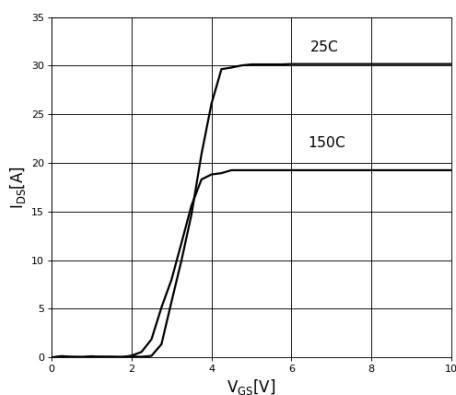


Figure 4. Typical Transfer Characteristics

$V_{DS} = 10\text{V}$, parameter: T_J

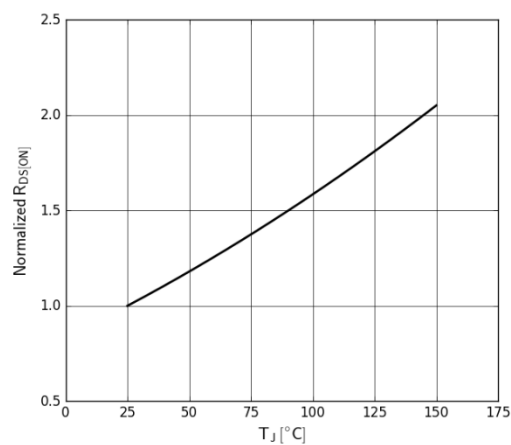


Figure 5. Normalized On-resistance

$I_D = 5\text{A}$, $V_{GS} = 6\text{V}$

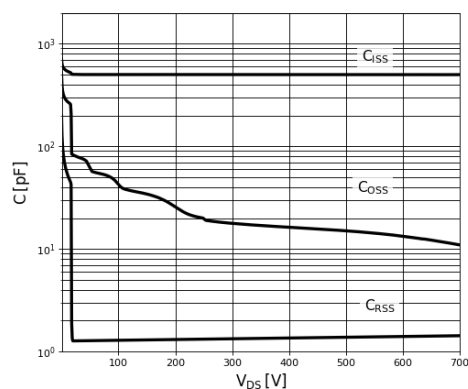


Figure 6. Typical Capacitance

$V_{GS} = 0\text{V}$, $f = 1\text{MHz}$

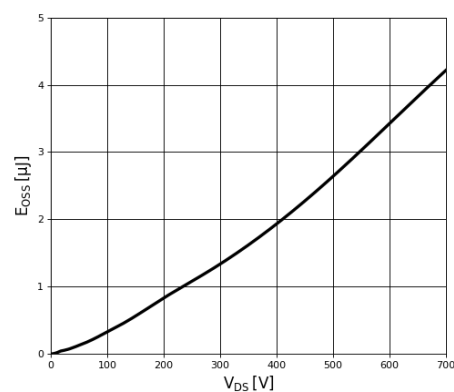


Figure 7. Typical C_{OSS} Stored Energy

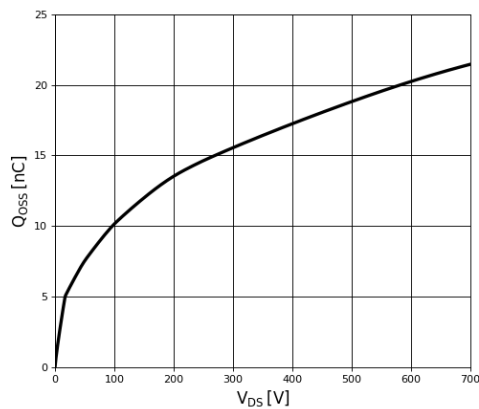


Figure 8. Typical Q_{oss}

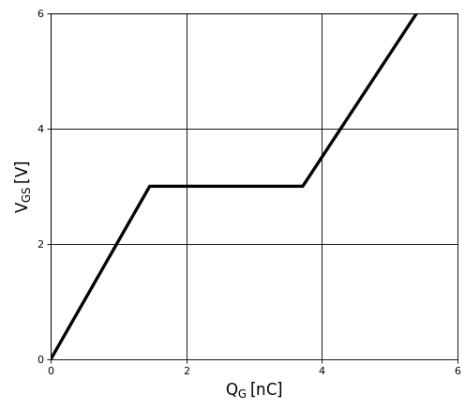


Figure 9. Typical Gate Charge

$I_{DS} = 5A$, $V_{DS} = 400V$

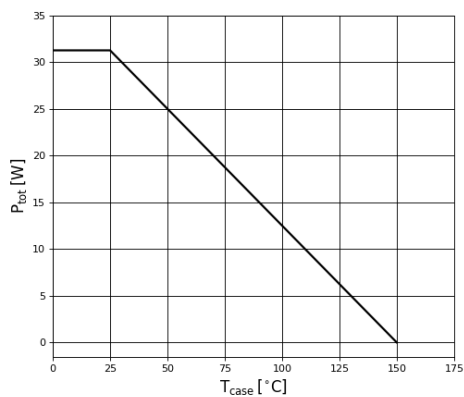


Figure 10. Power Dissipation

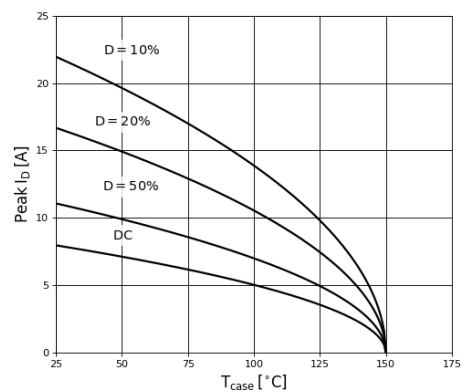


Figure 11. Current Derating

Pulse width $\leq 10\mu s$, $V_{GS} \geq 6V$

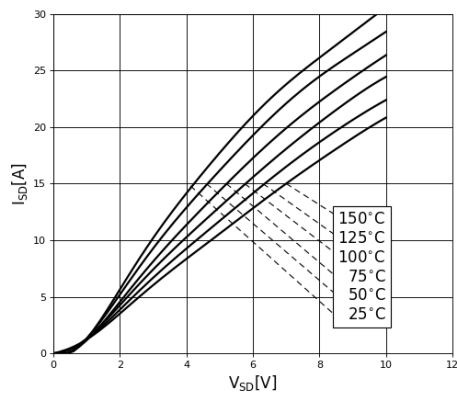


Figure 12. Forward Characteristics of Rev. Diode

$I_S = f(V_{SD})$, Parameter: T_J

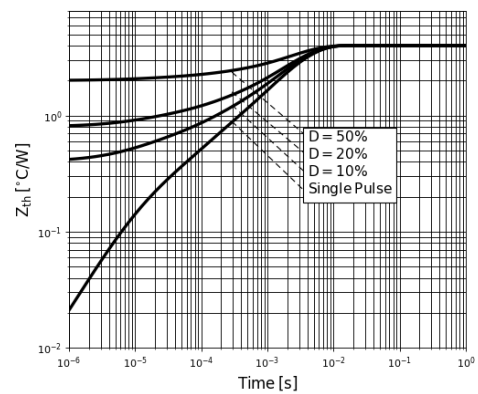


Figure 13. Transient Thermal Resistance

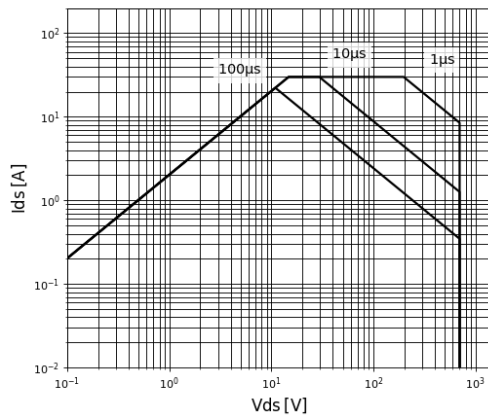


Figure 14. Safe Operating Area $T_c = 25^\circ\text{C}$

4. Test Circuits and Waveforms

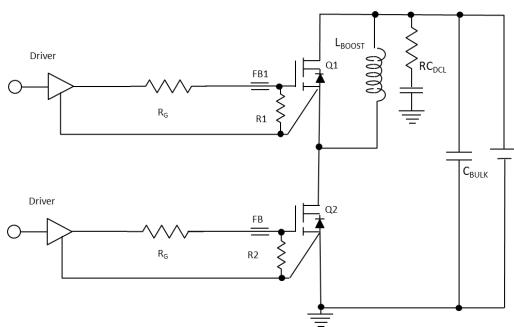


Figure 15. Switching Time Test Circuit

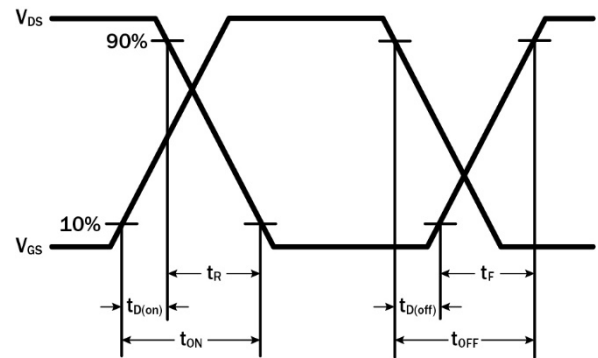


Figure 16. Switching Time Waveform

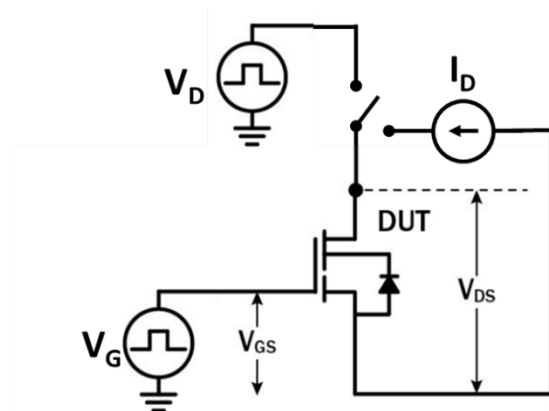


Figure 17. Dynamic $R_{DS(on)eff}$ Test Circuit

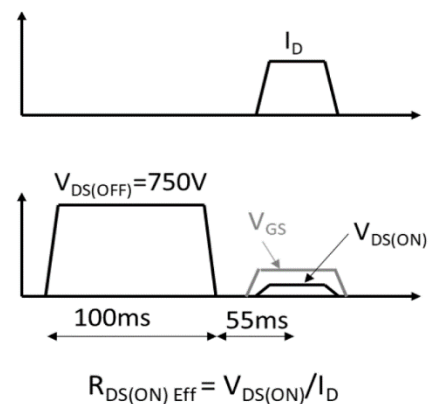


Figure 18. Dynamic $R_{DS(on)eff}$ Waveform

5. Package Outline Drawings

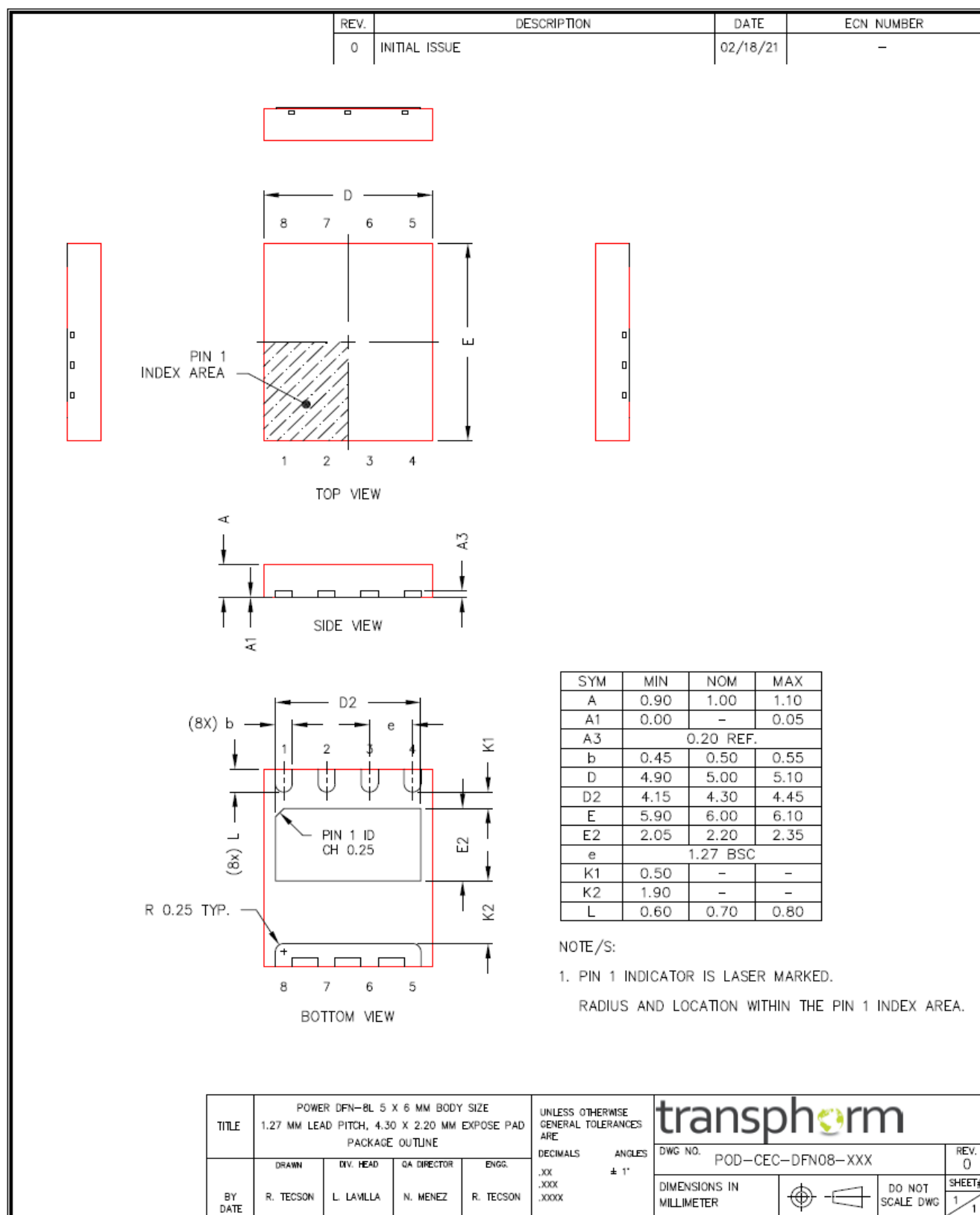


Figure 19. Package Outline Drawing – 5 × 6 PQFN

6. Related Information

All technical documents for Renesas GaN Power devices are accessible from the [GaN Power Solutions](#) page.

7. Ordering Information

Part Number	Package Description	Package Configuration
TP70H300G4JSGB-TR ^[1]	5 × 6 PQFN IP	Source

1. “-TR” suffix refers to tape and reel.

8. Revision History

Revision	Date	Description
2.00	Nov 21, 2025	Updated the document's formatting; no technical changes were completed
1.01	Sep 24, 2025	▪ Updated V_{GSS} maximum to 20V in section 2.1. ▪ Updated I_{GS} test voltage to $\pm 20V$ in section 2.4.
1.00	Apr 16, 2025	Initial release.

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